

9/2004 09/885,451 L18

FAST - Default Workspace [FastPanelLandscape.msp]

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Drafts
BRS:
Pending
Active

- L1: (4) ("6569299") or ("6521162") or ("6077419") or ("6332963")
- L2: (1) ("20030159936"). PN.
- L3: (1) ("20020023363"). PN.
- L4: (124390) anneals
- L5: (1) 13 and 14
- L6: (1201815) current
- L7: (1) 13 and 16
- L8: (5441) low adj K
- L9: (520) 18 same 14
- L10: (47428) electroplating or electrodeposits
- L11: (4110) electrochems near2 deposits
- L12: (49760) 110 or 111
- L13: (412817) copper or Cu
- L14: (17990) 112 same 113
- L15: (162) 19 and 114
- L16: (418) 114 and 18 and 14
- L17: (467451) semiconductor or semiconductors or wafer or wafer
- L18: (416) 116 and 117

Failed
Saved
Saved

Document ID	Issue/Date	Pages	Title	Current OR	Current Ref	Retrieval	CF	Inventor	U	S	C	P	FI	SI	PI
1	US 20040180541	20040916	12	Soft metal conductor and method of making	438/675	438/653;		Josh, Rajiv Vasant	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
2	US 20040180532	20040916	8	Method for forming a self-passivated copper	438/626	438/656;		Shue, Shau-lin et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
3	US 20040178060	20040916	18	Apparatus and method for depositing and planarizing	204/232	438/633		Kavkin, Mike et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
4	US 20040175929	20040909	14	Method of improving interlayer adhesion	438/628			Schmitt, Francimar	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
5	US 20040170753	20040902	13	Electrochemical mechanical processing using low	427/58	427/299		Campana et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
6	US 20040169255	20040902	24	Semiconductor device and method of manufacturing same	257/532			Basol, Bulent M.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
7	US 20040166783	20040826	24	Polishing apparatus and method	451/41			Kiyotoshi, Masahiro	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
8	US 20040166693	20040826	20	Sputtering target compositions, and methods of	438/785	204/192, 1;		Kimura, Norio et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
9	US 20040166665	20040826	18	Method of decreasing the K value in SiOC layer	438/622	438/638;		Li, Jianxing et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
10	US 20040164420	20040826	20	Sputtering target compositions, and methods of	257/763	438/758;		Gaillard, Frederic et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
11	US 20040159951	20040819	46	Semiconductor device and manufacturing method of	257/762	438/687		Li, Jianxing et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
12	US 20040157442	20040812	14	ROBUST VIA STRUCTURE AND METHOD	438/687			Toyoda, Hiroshi et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
13	US 20040157442	20040812	14	ROBUST VIA STRUCTURE AND METHOD	438/687			Cowley, Andy et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>

Search
D91
USPAT:US-PGPUB
Default operator: DR

116 and 117

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